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APPARATUS FOR SPLITTING SUBSTRATES, AND AN ASSOCIATED METHOD

The invention provides an apparatus for splitting a substrate apart, said substrate comprising two adjoining wafers defining between them a cleavage plane, the apparatus being characterized in that it comprises:

- means for feeding splitter means with a plurality of substrates disposed in a substrate-storage direction;
- splitter means for splitting apart the wafers of said substrates, the splitter means comprising moving jaws; and
- means for performing controlled displacement of certain substrate wafers after they have been split apart in a direction that is substantially parallel to the substrate-storage direction,

whereby the apparatus is suitable for splitting apart the plurality of substrates.

The invention also provides an associated splitting method.



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